WEST Search History

Hide Items | Restore | Clear | Cancel

DATE: Tuesday, April 19, 2005

Hide?	Set Name	Query	Hit Count
	DB=PGPB; PLUR=YES; OP=ADJ		
☐	L13	US-20040163670-A1.did.	1
	DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ		
☐	L12	L10 and (scanning solution)	5
☐	L11	L10 and coher	0
☐	L10	scanning nozzle	237
☐	L9	l3 and 134/$.ccls.	14
☐	L8	L7 and solution	42
☐	L7	L6 and collecting	42
☐	L6	L5 and wafer	228
☐	L5	L4 and coher$	246
☐	L4	L3 and arm	825
☐	L3	l1 and scanning	3423
☐	L2	nozzle and capillary	19127
☐	L1	nozzle and capillary	19127

END OF SEARCH HISTORY

Hit List

Clear | Generate Collection | Print | Fwd Refs | Bkwd Refs | Generate OACS

Search Results - Record(s) 1 through 5 of 5 returned.

☐ 1. Document ID: US 20050058944 A1

Using default format because multiple data bases are involved.

L12: Entry 1 of 5 File: PGPB Mar 17, 2005

PGPUB-DOCUMENT-NUMBER: 20050058944
PGPUB-FILING-TYPE: new
DOCUMENT-IDENTIFIER: US 20050058944 A1

TITLE: Alkaline solution and manufacturing method, and alkaline solution applied to patern forming method, resist film removing method, solution application method, substrate treatment method, solotion supply method, and semiconductor device manufacturing method

PUBLICATION-DATE: March 17, 2005

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Takahashi, Riichiro	Yokohama-shi		JP	
Hayasaki, Kei	Kamakura-shi		JP	
Takeishi, Tomoyuki	Yokohama-shi		JP	
Ito, Shinichi	Yokohama-shi		JP	

US-CL-CURRENT: 430/311

Full | Title | Citation | Front | Review | Classification | Date | Reference | Sequences | Attachments | Claims | KWIC | Draw D

☐ 2. Document ID: US 20040163670 A1

L12: Entry 2 of 5 File: PGPB Aug 26, 2004

PGPUB-DOCUMENT-NUMBER: 20040163670
PGPUB-FILING-TYPE: new
DOCUMENT-IDENTIFIER: US 20040163670 A1

TITLE: Apparatus and method for collecting impurities on a semiconductor wafer

PUBLICATION-DATE: August 26, 2004

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Ko, Yong-Kyun	Osan-city		KR	

Son, Byung-Woo	Yongin-city	KR
Jeong, Jong-Cheol	Gyeonggi-do	KR

US-CL-CURRENT: 134/2; 134/148, 134/153, 134/25.4, 134/34, 134/902

ABSTRACT:

An apparatus for collecting impurities on a semiconductor wafer includes an airtight process chamber, a rotary chuck disposed in the process chamber for rotating and horizontally supporting the semiconductor wafer, a first scanning unit for forming a droplet of a first scanning solution and for scanning an upper surface of the semiconductor wafer rotated by the rotary chuck with the droplet to collect first impurities, a driving unit for tilting the rotary chuck and the semiconductor wafer supported on the rotary chuck, and a second scanning unit for receiving a second scanning solution for collecting second impurities from an edge portion of the semiconductor wafer, the second scanning solution being in contact with the edge portion of the semiconductor wafer tilted by the driving unit and rotated by the rotary chuck so that the second scanning solution scans the edge portion of the semiconductor wafer.

☐ 3. Document ID: US 20030068579 A1

L12: Entry 3 of 5 File: PGPB Apr 10, 2003

PGPUB-DOCUMENT-NUMBER: 20030068579
PGPUB-FILING-TYPE: new
DOCUMENT-IDENTIFIER: US 20030068579 A1

TITLE: Alkaline solution and manufacturing method, and alkaline solution applied to pattern forming method, resist film removing method, solution application method, substrate treatment method, solution supply method, and semiconductor device manufacturing method

PUBLICATION-DATE: April 10, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Takahashi, Riichiro	Yokohama-shi		JP	
Hayasaki, Kei	Kamakura-shi		JP	
Takeishi, Tomoyuki	Yokohama-shi		JP	
Ito, Shinichi	Yokohama-shi		JP	

US-CL-CURRENT: 430/311; 118/52, 134/102.1, 134/2, 134/34, 134/64P, 134/88, 396/579, 396/611, 430/325, 430/327, 430/329, 430/331, 510/175, 510/176, 510/370, 510/372, 510/405

ABSTRACT:

A manufacturing method of an alkaline solution, comprising dissolving a gaseous molecule having oxidizing properties or reducing properties in an aqueous alkaline

solution.

4. Document ID: US 6742944 B2

L12: Entry 4 of 5 File: USPT Jun 1, 2004

US-PAT-NO: 6742944
DOCUMENT-IDENTIFIER: US 6742944 B2

TITLE: ALKALINE SOLUTION AND MANUFACTURING METHOD, AND ALKALINE SOLUTION APPLIED TO PATTERN FORMING METHOD, RESIST FILM REMOVING METHOD, SOLUTION APPLICATION METHOD, SUBSTRATE TREATMENT METHOD, SOLUTION SUPPLY METHOD, AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD

DATE-ISSUED: June 1, 2004

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Takahashi; Riichiro	Yokohama			JP
Hayasaki; Kei	Kamakura			JP
Takeishi; Tomoyuki	Yokohama			JP
Ito; Shinichi	Yokohama			JP

US-CL-CURRENT: 396/611; 118/677, 118/679, 396/327

ABSTRACT:

A manufacturing method of an alkaline solution, comprising dissolving a gaseous molecule having oxidizing properties or reducing properties in an aqueous alkaline solution.

12 Claims, 64 Drawing figures
Exemplary Claim Number: 1
Number of Drawing Sheets: 19

5. Document ID: KR 2004075564 A, US 20040163670 A1

L12: Entry 5 of 5 File: DWPI Aug 30, 2004

DERWENT-ACC-NO: 2004-641419
DERWENT-WEEK: 200504

TITLE: Semiconductor wafer impurity collection apparatus for semiconductor device manufacture, has scanning units to scan upper surface and edge of wafer with scanning solutions to collect metallic impurities respectively

INVENTOR: JUNG, J C; KO, Y G ; SON, B U ; JEONG, J ; KO, Y ; SON, B

PRIORITY-DATA: 2003KR-0011109 (February 21, 2003)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
KR 2004075564 A	August 30, 2004		000	H01L021/02
US 20040163670 A1	August 26, 2004		025	B08B003/02

INT-CL (IPC): B08 B 3/02; H01 L 21/02

Clear | Generate Collection | Print | Fwd Refs | Bkwd Refs | Generate OACS

Term	Documents
SCANNING	560437
SCANNINGS	2734
SOLUTION	4858600
SOLN	446763
SOLNS	52696
SOLUTIONS	717436
(10 AND (SCANNING ADJ SOLUTION)).PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD.	5
(L10 AND (SCANNING SOLUTION)).PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD.	5

Display Format: - Change Format

Previous Page Next Page Go to Doc#